

#### 3A SBR<sup>®</sup> SUPER BARRIER RECTIFER

#### Features

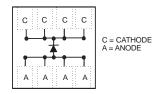
- Ultra Low Forward Voltage Drop
- Superior Reverse Avalanche Capability
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- Lead Free Finish, RoHS Compliant (Note 1)
- "Green" Molding Compound Device (Note 2)



## **Mechanical Data**

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- Case: DFN3030-8
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish NiPdAu annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208 <sup>(C3)</sup>
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.0172 grams (approximate)



Bottom View

Device Schematic

## **Maximum Ratings** $@T_A = 25^{\circ}C$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

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Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	100	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	70	V
Average Rectified Output Current	lo	3.0	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	32	A

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance	R <sub>θJA</sub>	61	°C/W
Thermal Resistance Junction to Ambient (Note 3) T <sub>A</sub> = 25°C	ιν <sub>θ</sub> JA		0/11
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	٦°

### Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	V <sub>(BR)R</sub>	100	-	-	V	I <sub>R</sub> = 1mA
Forward Voltage	VF	- - -	0.44 0.67 0.42 0.58	0.48 0.71 0.45 0.61	V	$\begin{split} I_F &= 1.0A, \ T_J = 25^{\circ}C \\ I_F &= 3.0A, \ T_J = 25^{\circ}C \\ I_F &= 1.0A, \ T_J = 125^{\circ}C \\ I_F &= 3.0A, \ T_J = 125^{\circ}C \end{split}$
Reverse Current (Note 4)	I <sub>R</sub>	-	16 3	200 15	μA mA	$V_R = 100V, T_J = 25^{\circ}C$ $V_R = 100V, T_J = 125^{\circ}C$

Notes: 1. RoHS revision 13.2.2003. High temperature solder exemption applied, see *EU Directive Annex Note* 7.

2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php

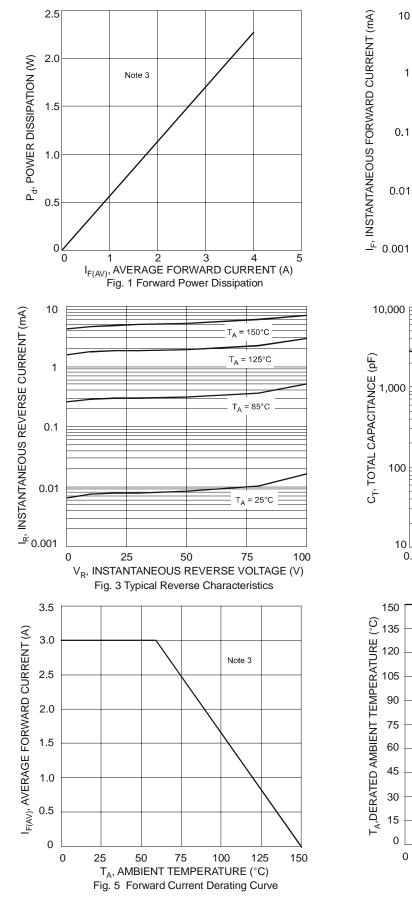
3. Device mounted on Polyimide substrate, 2 oz. Copper, 75mm<sup>2</sup> pad area, double side PCB.

4. Short duration pulse test used to minimize self-heating effect.

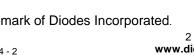
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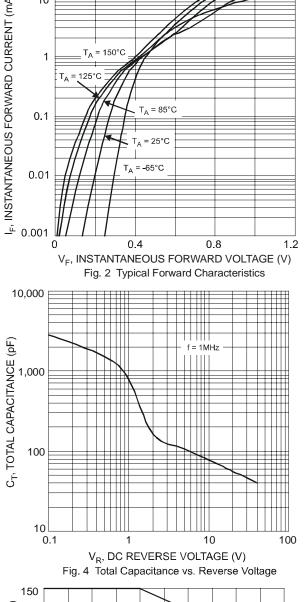


## SBR3U100LP



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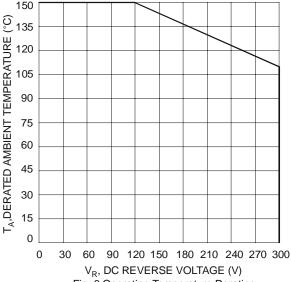


Fig. 6 Operating Temperature Derating

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#### Ordering Information (Note 6)

Part Number	Case	Packaging
SBR3U100LP-7	DFN3030-8	3000/Tape & Reel

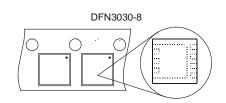
Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

### Marking Information

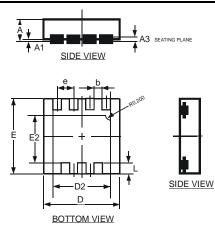
NEW PRODUCT



3U10 = Product marking code YYWW = Date code marking YY = Last digit of year ex: 06 for 2006 WW = Week code 01 to 52

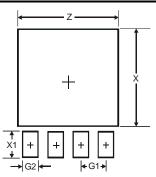


## **Package Outline Dimensions**



DFN3030-8				
Dim	Min	Max	Тур	
Α	0.57	0.63	0.60	
A1	0	0.05	0.02	
A3			0.15	
b	0.29	0.39	0.34	
D	2.90	3.10	3.00	
D2	2.19	2.39	2.29	
е			0.65	
ш	2.90	3.10	3.00	
E2	1.64	1.84	1.74	
L	0.30	0.60	0.45	
All Dimensions in mm				

## Suggested Pad Layout



Dimensions	Value (in mm)
G1	0.65
G2	0.39
Х	2.49
X1	0.65
Z	2.59

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